



## **ChipMOS FILES PATENT INFRINGEMENT SUIT AGAINST WALTON ADVANCED ENGINEERING INC.**

HSINCHU, Taiwan, Sept. 5, 2007 -- ChipMOS TECHNOLOGIES (Bermuda) LTD. ("ChipMOS" or the "Company") (Nasdaq: IMOS) announced today that its 99.14% owned subsidiary, ChipMOS TECHNOLOGIES INC. ("ChipMOS Taiwan") filed a lawsuit on September 5, 2007.

Taiwan time in Kaohsiung District Court against Walton Advanced Engineering, Inc. ("Walton"), alleging infringement by Walton of two of ChipMOS Taiwan's BGA (Ball Grid Array) package related patents which are used for DDR II SDRAM devices.

ChipMOS Taiwan obtained from the retail market several branded memory modules packaged by Walton and sent them to a professional appraisal institution for investigation. ChipMOS Taiwan decided to file the litigation based upon the investigating report of this professional appraisal institution, which concluded that the package device employed on the aforementioned modules infringed ChipMOS Taiwan R.O.C. patent no. 207627 "Substrate on Chip Packaging Process" and patent no. 207525 "Substrate on Chip Packaging Process".

For Patent Summary, please refer to the link: <http://xprnnews.xfn.info/chipmos/patent.htm> .

ChipMOS highly values intellectual property while continuously focusing on the R&D of advanced technology and products. As of July 31, 2007, ChipMOS and ChipMOS Taiwan have accumulated 456 registered and active patents, which is a key factor in the Company's leading status of memory and LCD driver SATS (Semiconductor Assembly and Test Services) industry. In order to protect its patents and shareholders' rights, ChipMOS Taiwan decided to file the patent infringement lawsuit against Walton, seeking NT\$15 million in monetary damages at the initial stage for the losses ChipMOS Taiwan suffered as well as a court order prohibiting Walton from using the allegedly infringing technology.

About ChipMOS TECHNOLOGIES (Bermuda) LTD.:

ChipMOS ( <http://www.chipmos.com/> ) is a leading independent provider of semiconductor testing and assembly services to customers in Taiwan, Japan, and the U.S. With advanced facilities in Hsinchu and Southern Taiwan Science Parks in Taiwan and Shanghai, ChipMOS and its subsidiaries provide testing and assembly services to a broad range of customers, including leading fabless semiconductor companies, integrated device manufacturers and independent semiconductor foundries.

### **Forward-Looking Statements**

Certain statements contained in this announcement may be viewed as "forward-looking statements" within the meaning of Section 27A of the U.S. Securities Act of 1933, as amended, and Section 21E of the U.S. Securities Exchange Act of 1934, as amended. Such forward-looking statements involve known and unknown risks, uncertainties and other factors, which may cause the actual performance, financial condition or results of operations of the Company to be materially different from any future performance, financial condition or results of operations implied by such forward-looking statements. Further information regarding these risks, uncertainties and other factors is included in the Company's most recent Annual Report on Form 20-F filed with the U.S. Securities and Exchange Commission (the "SEC") and in the Company's other filings with the SEC.